

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-3. (canceled)

4. (currently amended) A low-pin-count chip package comprising:
a die pad and a plurality of connection pads arranged around ~~at the periphery~~ of the die pad wherein the die pad and the connection pads have a concave profile;
a first metal coating on the upper surface of the die pad and the connection pads;
a semiconductor chip disposed on the die pad and electrically coupled to the connection pads;
a package body formed over the semiconductor chip and the connection pads in a manner that a portion of the die pad and a portion of each connection pad extend outward from the bottom of the package body; and
a second metal coating on the lower surface of the die pad and the connection pads,
wherein each of the die pad and the connection pads has a first portion embedded in the package body and a second portion located outside the package body, both the first and second portions have concave profiles.

5. (original) The low-pin-count chip package as claimed in claim 4, wherein each of the first and the second metal coating comprises a layer of nickel covering the surface of the die pad and the connection pads, and a layer of metal selected from the group consisted of gold and palladium covering the nickel layer.

6. (original) The low-pin-count chip package as claimed in claim 4, wherein the

extension portions of the die pad and each connection pad have a height of at least 2 mils.

7. (original) The low-pin-count chip package as claimed in claim 4, wherein areas on the surfaces of the die pad and each connection pad without protection of the package body have a third metal coating formed thereon thereby avoiding corrosion and contamination.

8-14. (canceled)

15. (previously presented) The chip package of claim 4, wherein each of the die pad and connection pads is a piece made of a single material which projects integrally from within the package body outwardly and beyond a bottom surface of the package body.

16. (previously presented) The chip package of claim 15, wherein said single material is copper.

17. (previously presented) The chip package of claim 15, wherein said piece has a first portion embedded in the package body and a second portion located outside the package body, said second portion having a lower surface covered by the second metal coating and side surfaces uncovered by the second metal coating, said chip package further comprising a third metal coating covering the side surfaces of the second portion and the second metal coating.

18-22. (canceled)